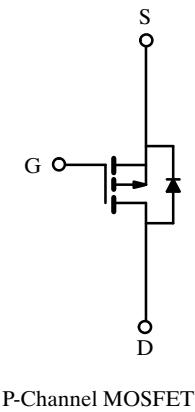
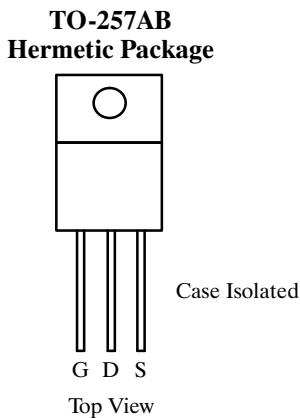


P-Channel Enhancement-Mode Transistor**Product Summary**

$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ (Ω)	I_D (A)
-100	0.30	-10

**Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ Unless Otherwise Noted)**

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-100	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 150^\circ\text{C}$)	I_D	-10	A
		-6.7	
Pulsed Drain Current	I_{DM}	-40	
Maximum Power Dissipation	P_D	60	W
		24	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ\text{C}$
Lead Temperature ($1/16''$ from case for 10 sec.)	T_L	300	

Thermal Resistance Ratings

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient	R_{thJA}		80	$^\circ\text{C/W}$
Maximum Junction-to-Case	R_{thJC}		2.0	
Case-to-Sink	R_{thCS}	1.0		

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Specifications ($T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Limit			Unit
			Min	Typ ^a	Max	
Static						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-100			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250 \mu\text{A}$	-2.0		-4.0	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0 \text{ V}, V_{\text{GS}} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -80 \text{ V}, V_{\text{GS}} = 0 \text{ V}$			-25	μA
		$V_{\text{DS}} = -80 \text{ V}, V_{\text{GS}} = 0 \text{ V}, T_J = 125^\circ\text{C}$			-250	
On-State Drain Current ^b	$I_{\text{D}(\text{on})}$	$V_{\text{DS}} = -10 \text{ V}, V_{\text{GS}} = -10 \text{ V}$	-10			A
Drain-Source On-State Resistance ^b	$r_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10 \text{ V}, I_D = -6.7 \text{ A}$		0.25	0.30	Ω
		$V_{\text{GS}} = -10 \text{ V}, I_D = -6.7 \text{ A}, T_J = 125^\circ\text{C}$		0.4	0.53	
Forward Transconductance ^b	g_{fs}	$V_{\text{DS}} = -15 \text{ V}, I_D = -6.7 \text{ A}$	2.0	3.0		S
Dynamic						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0 \text{ V}, V_{\text{DS}} = -25 \text{ V}, f = 1 \text{ MHz}$		625		pF
Output Capacitance	C_{oss}			280		
Reverse Transfer Capacitance	C_{rss}			105		
Total Gate Charge ^c	Q_g	$V_{\text{DS}} = -50 \text{ V}, V_{\text{GS}} = -10 \text{ V}, I_D = -10 \text{ A}$		24	40	nC
Gate-Source Charge ^c	Q_{gs}			3.4	6.0	
Gate-Drain Charge ^c	Q_{gd}			13.5	20	
Turn-On Delay Time ^c	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = -50 \text{ V}, R_L = 5 \Omega$ $I_D \approx -10 \text{ A}, V_{\text{GEN}} = 10 \text{ V}, R_G = 7.5 \Omega$		9	60	ns
Rise Time ^c	t_r			50	140	
Turn-Off Delay Time ^c	$t_{\text{d}(\text{off})}$			60	140	
Fall Time ^c	t_f			38	140	
Source-Drain Diode Ratings and Characteristics						
Continuous Current	I_S				-10	A
Pulsed Current	I_{SM}				-40	
Diode Forward Voltage ^b	V_{SD}	$I_F = 10 \text{ A}, V_{\text{GS}} = 0 \text{ V}$			-2.0	V
Reverse Recovery Time	t_{rr}	$I_F = 10 \text{ A}, \text{di/dt} = 100 \text{ A}/\mu\text{s}$		110	250	ns
Reverse Recovery Charge	Q_{rr}			0.4		μC

Notes:

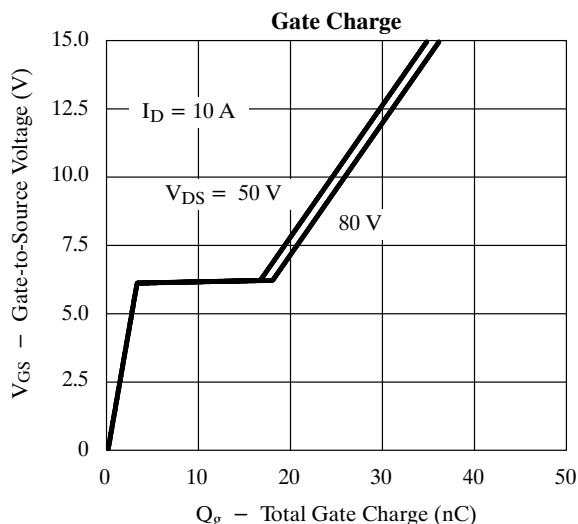
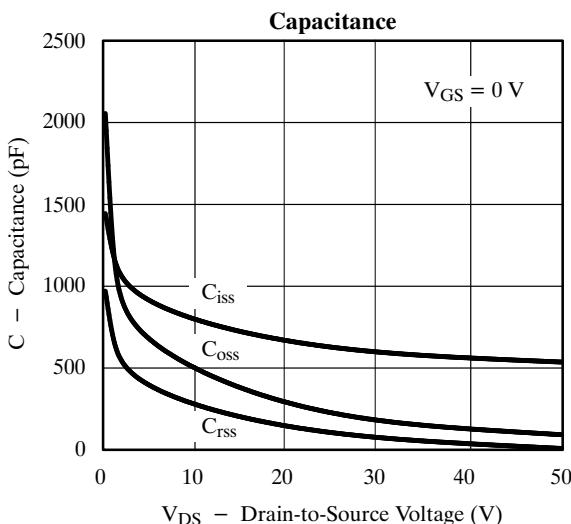
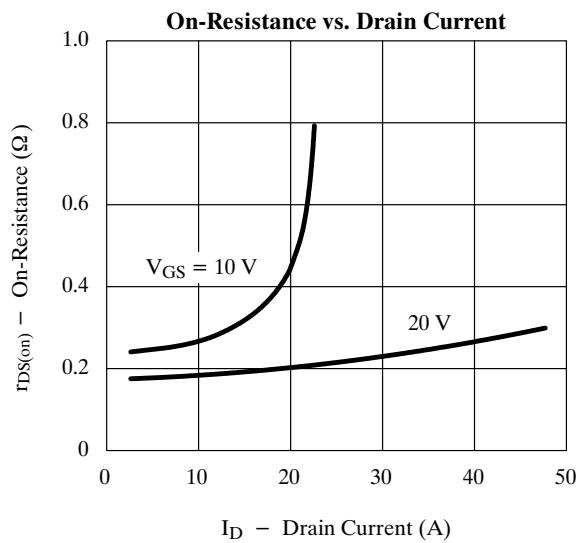
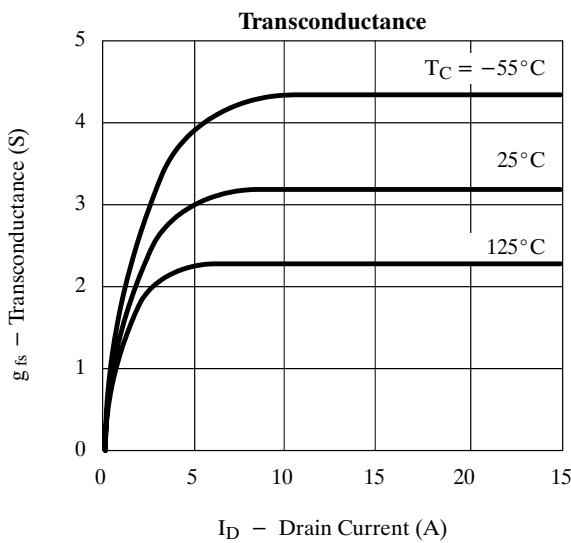
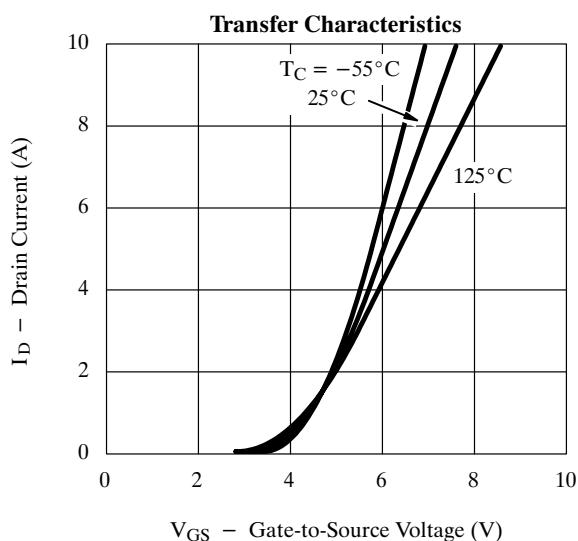
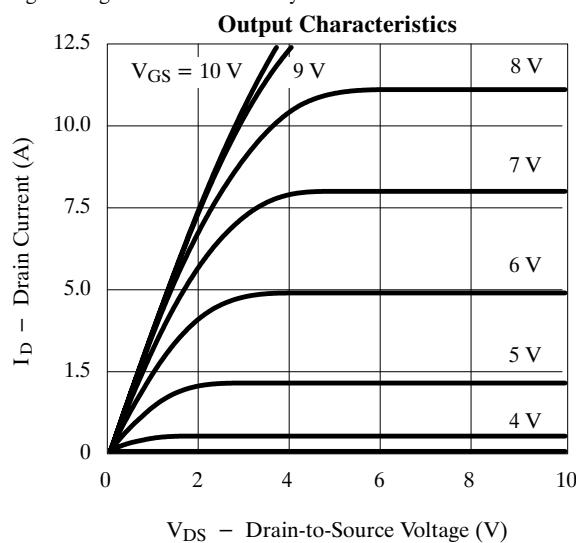
a. For design aid only; not subject to production testing.

b. Pulse test; pulse width duty cycle 2%.

c. Independent of operating temperature.

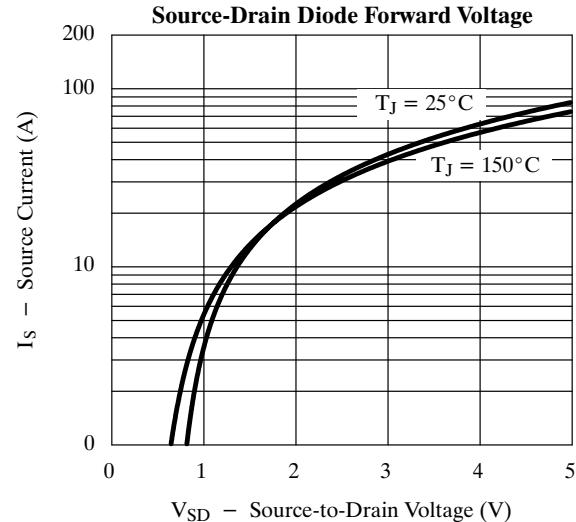
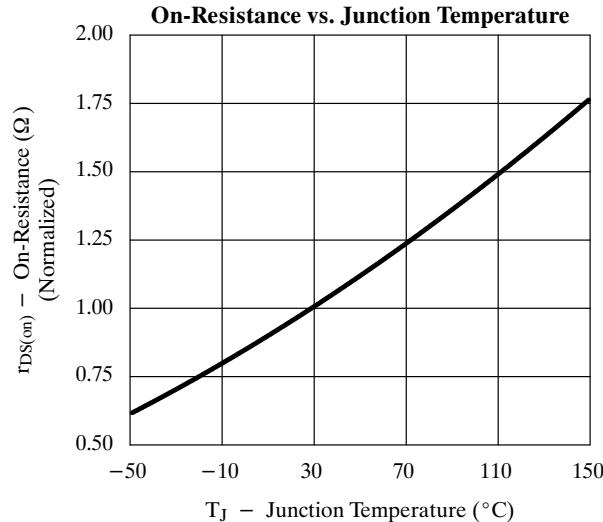
Typical Characteristics (25°C Unless Otherwise Noted)

Negative signs omitted for clarity.



2N7089**Typical Characteristics (25°C Unless Otherwise Noted)**

Negative signs omitted for clarity.

**Thermal Ratings**